

# PESD5V0S1UJ; PESD12VS1UJ

Unidirectional ESD protection for transient voltage suppression

Rev. 01 — 3 June 2009

Product data sheet

## 1. Product profile

### 1.1 General description

Unidirectional ElectroStatic Discharge (ESD) protection diodes in a very small Surface-Mounted Device (SMD) plastic package designed to protect one signal line from the damage caused by ESD and transient overvoltage.

Table 1. Product overview

Type number	Package		Configuration
	NXP	JEITA	
PESD5V0S1UJ	SOD323F	SC-90	single
PESD12VS1UJ			

### 1.2 Features

- Transient Voltage Suppression (TVS) protection of one line
- Max. peak pulse power:  $P_{PP} = 890$  W
- Low clamping voltage:  $V_{CL} = 19$  V
- Low leakage current:  $I_{RM} = 300$  nA
- ESD protection up to 30 kV
- IEC 61000-4-2; level 4 (ESD)
- IEC 61000-4-5 (surge);  $I_{PP} = 47$  A
- AEC-Q101 qualified

### 1.3 Applications

- Computers and peripherals
- Audio and video equipment
- Cellular handsets and accessories
- Communication systems
- Portable electronics
- Medical and industrial equipment

### 1.4 Quick reference data


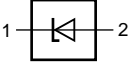
Table 2. Quick reference data

$T_{amb} = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RWM}$	reverse standoff voltage					
	PESD5V0S1UJ		-	-	5	V
	PESD12VS1UJ		-	-	12	V
$C_d$	diode capacitance	$f = 1$ MHz; $V_R = 0$ V				
	PESD5V0S1UJ		-	480	530	pF
	PESD12VS1UJ		-	160	180	pF

## 2. Pinning information

**Table 3. Pinning**

Pin	Description	Simplified outline	Graphic symbol
1	cathode <sup>[1]</sup>		 006aaa152
2	anode		

[1] The marking bar indicates the cathode.

## 3. Ordering information

**Table 4. Ordering information**

Type number	Package		
	Name	Description	Version
PESD5V0S1UJ	SC-90	plastic surface-mounted package; 2 leads	SOD323F
PESD12VS1UJ			

## 4. Marking

**Table 5. Marking codes**

Type number	Marking code
PESD5V0S1UJ	1Q
PESD12VS1UJ	1R

## 5. Limiting values

**Table 6. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
P <sub>PP</sub>	peak pulse power	t <sub>p</sub> = 8/20 μs	[1][2]		
	PESD5V0S1UJ		-	890	W
	PESD12VS1UJ		-	600	W
I <sub>PP</sub>	peak pulse current	t <sub>p</sub> = 8/20 μs	[1][2]		
	PESD5V0S1UJ		-	47	A
	PESD12VS1UJ		-	22.5	A

**Table 6. Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[3] -	420	mW
			[4] -	720	mW
T <sub>j</sub>	junction temperature		-	150	°C
T <sub>amb</sub>	ambient temperature		-55	+150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

[1] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.

[2] Soldering point of cathode tab.

[3] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

**Table 7. ESD maximum ratings**

T<sub>amb</sub> = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>ESD</sub>	electrostatic discharge voltage	IEC 61000-4-2 (contact discharge)	[1] -	30	kV
		machine model	-	400	V
		MIL-STD-883 (human body model)	-	16	kV

[1] Device stressed with ten non-repetitive ESD pulses.

**Table 8. ESD standards compliance**

Standard	Conditions
IEC 61000-4-2; level 4 (ESD)	> 15 kV (air); > 8 kV (contact)
MIL-STD-883; class 3 (human body model)	> 4 kV

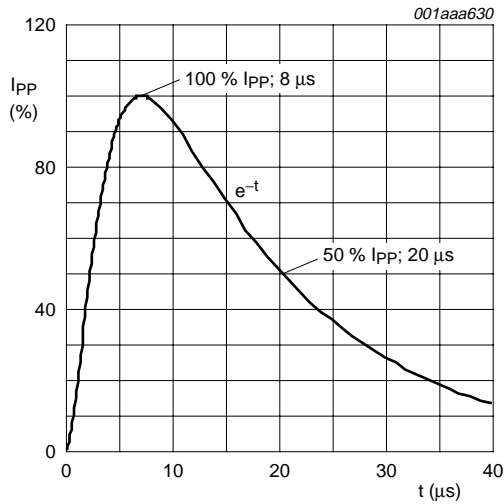


Fig 1. 8/20 μs pulse waveform according to IEC 61000-4-5

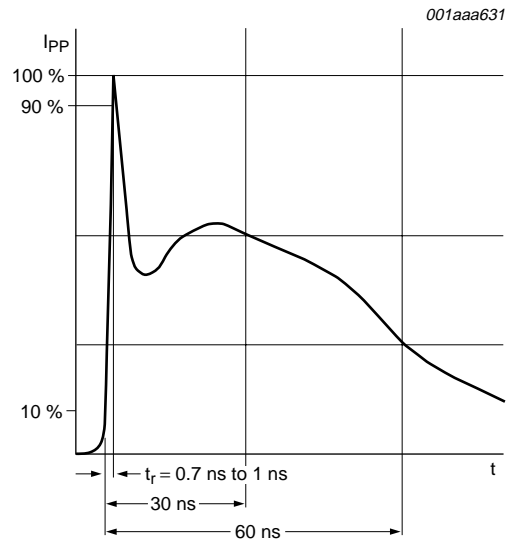


Fig 2. ESD pulse waveform according to IEC 61000-4-2

## 6. Thermal characteristics

Table 9. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1]	-	290	K/W
			[2]	-	170	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		[3]	-	35	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

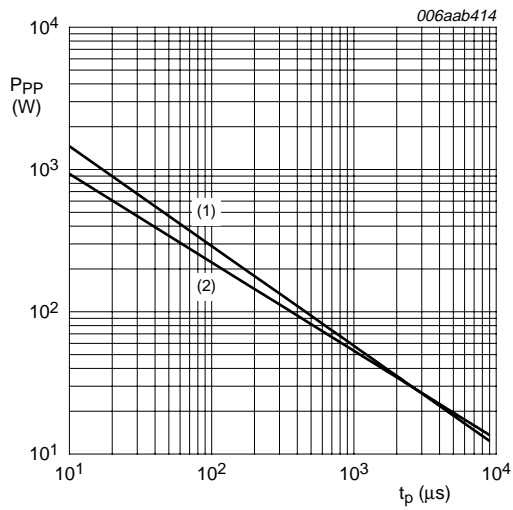
[3] Soldering point of cathode tab.

## 7. Characteristics

**Table 10. Characteristics**
*T<sub>amb</sub> = 25 °C unless otherwise specified.*

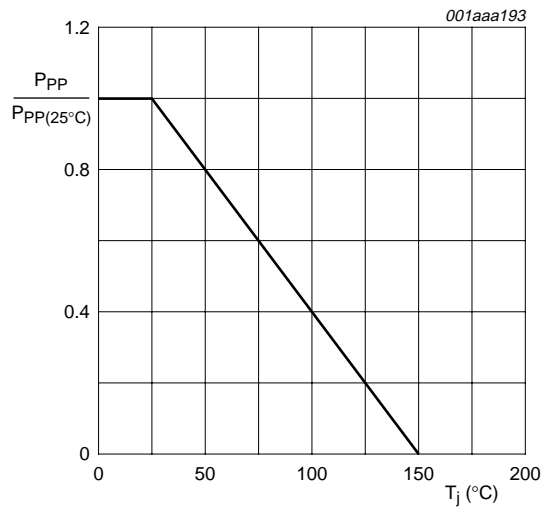
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>RWM</sub>	reverse standoff voltage					
	PESD5V0S1UJ		-	-	5	V
	PESD12VS1UJ		-	-	12	V
I <sub>RM</sub>	reverse leakage current					
	PESD5V0S1UJ	V <sub>RWM</sub> = 5 V	-	0.3	4	μA
	PESD12VS1UJ	V <sub>RWM</sub> = 12 V	-	< 1	100	nA
V <sub>BR</sub>	breakdown voltage	I <sub>R</sub> = 5 mA				
	PESD5V0S1UJ		6.2	6.8	7.3	V
	PESD12VS1UJ		13.3	14.5	15.75	V
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 0 V				
	PESD5V0S1UJ		-	480	530	pF
	PESD12VS1UJ		-	160	180	pF
V <sub>CL</sub>	clamping voltage		[1]			
	PESD5V0S1UJ	I <sub>PP</sub> = 47 A	-	-	19	V
		I <sub>PP</sub> = 25 A	-	-	13.5	V
		I <sub>PP</sub> = 5 A	-	-	9.8	V
	PESD12VS1UJ	I <sub>PP</sub> = 22.5 A	-	-	27	V
		I <sub>PP</sub> = 15 A	-	-	23.5	V
I <sub>PP</sub> = 5 A		-	-	19	V	
r <sub>dif</sub>	differential resistance	I <sub>R</sub> = 5 mA				
	PESD5V0S1UJ		-	2	100	Ω
	PESD12VS1UJ		-	5	100	Ω

[1] Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC 61000-4-5.

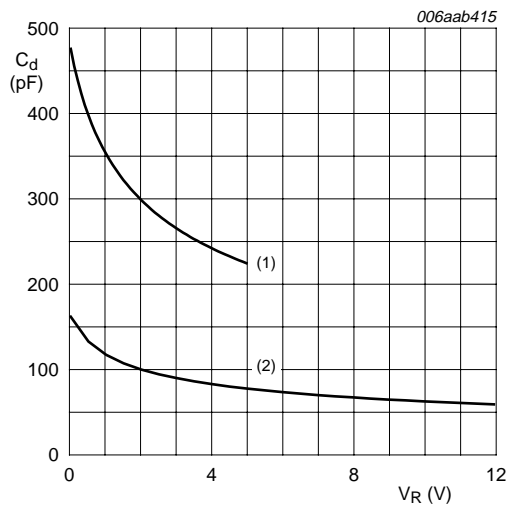


$T_{amb} = 25\text{ }^\circ\text{C}$   
 (1) PESD5V0S1UJ  
 (2) PESD12VS1UJ

**Fig 3. Peak pulse power as a function of exponential pulse duration; typical values**

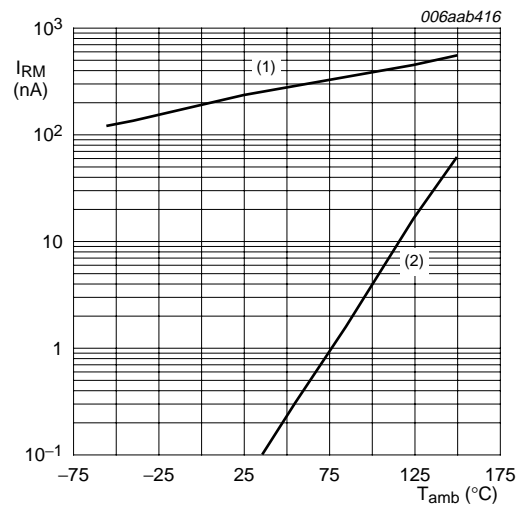


**Fig 4. Relative variation of peak pulse power as a function of junction temperature; typical values**



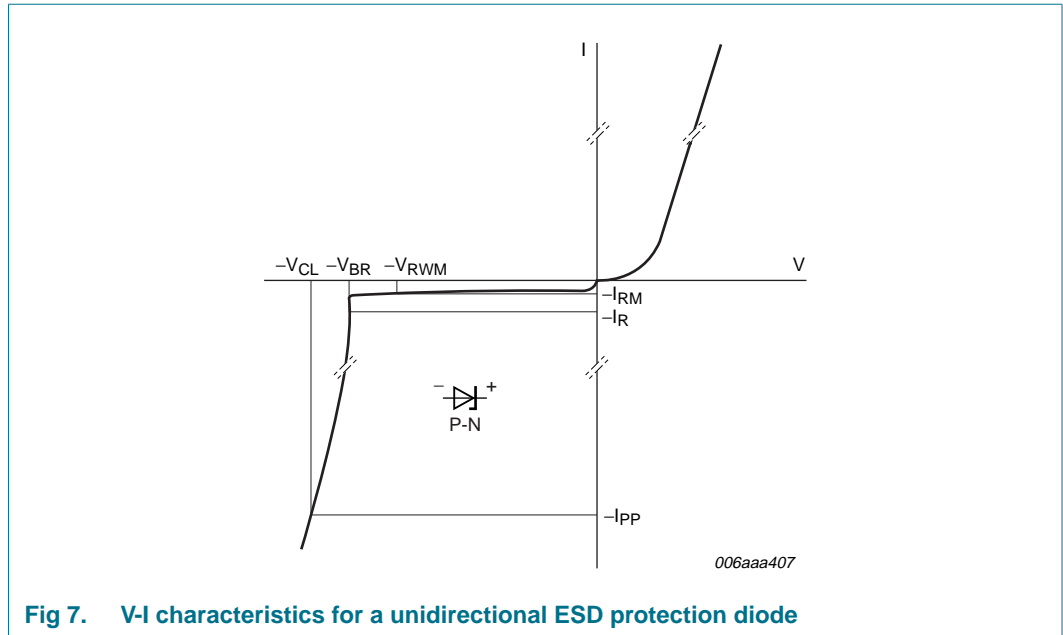
$f = 1\text{ MHz}; T_{amb} = 25\text{ }^\circ\text{C}$   
 (1) PESD5V0S1UJ  
 (2) PESD12VS1UJ

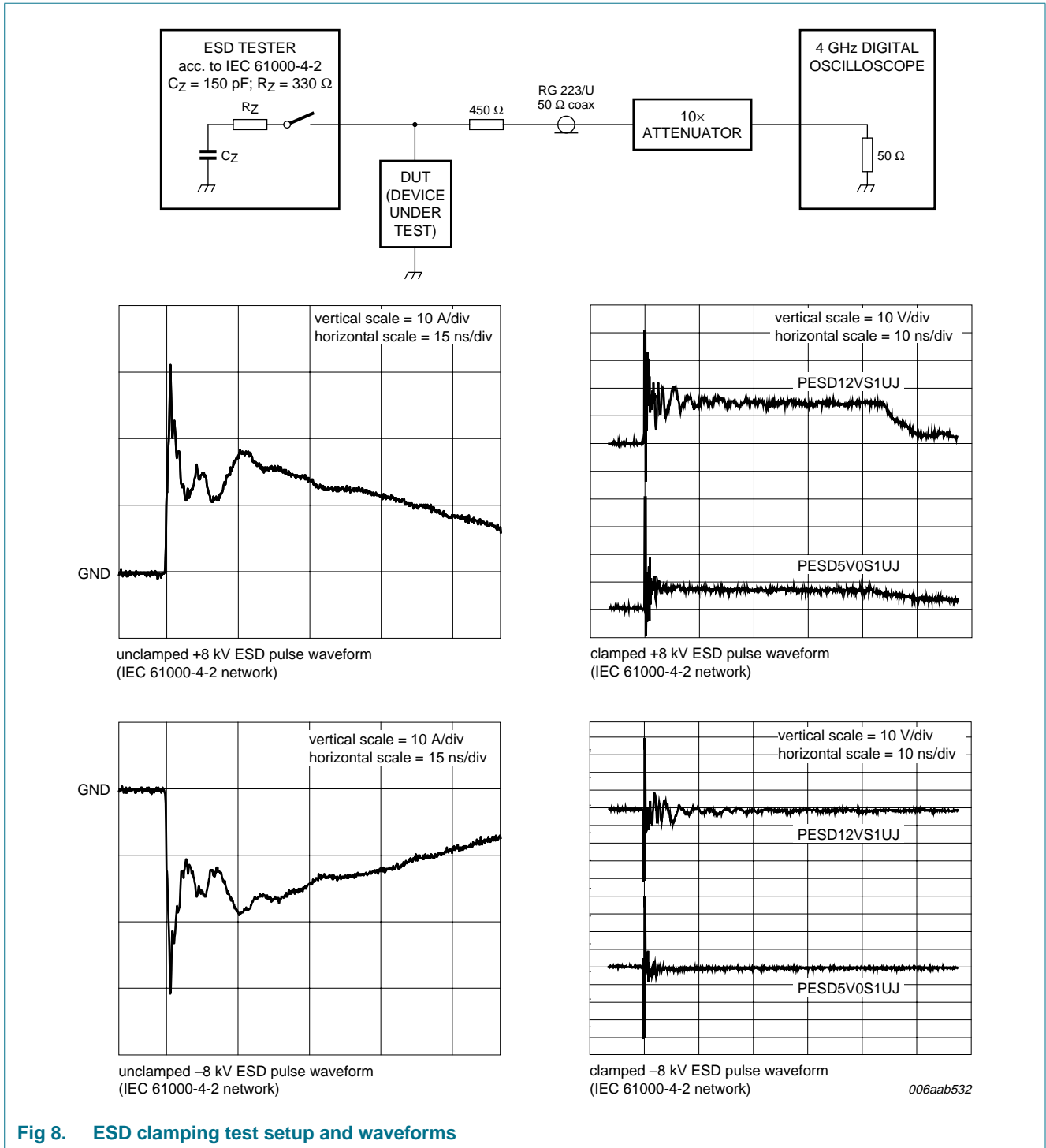
**Fig 5. Diode capacitance as a function of reverse voltage; typical values**



(1) PESD5V0S1UJ  
 (2) PESD12VS1UJ

**Fig 6. Reverse leakage current as a function of ambient temperature; typical values**





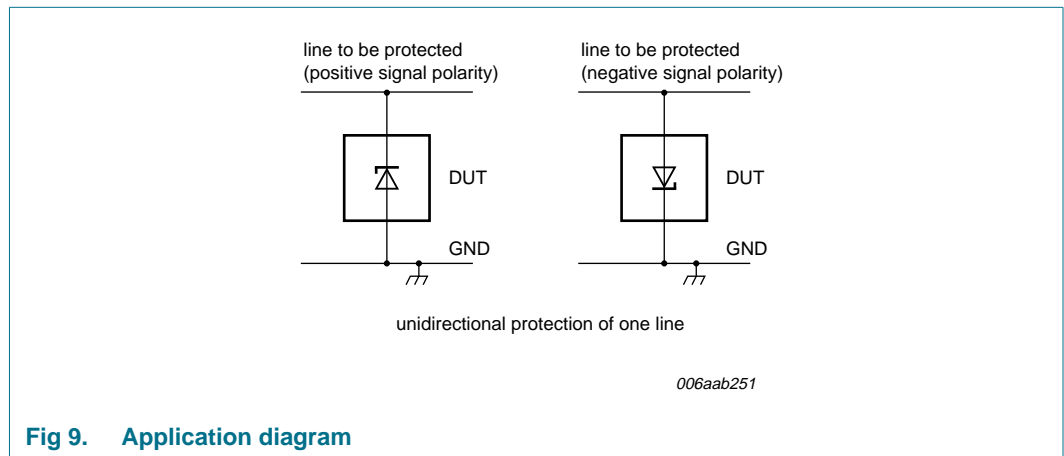
**Fig 8. ESD clamping test setup and waveforms**



## 8. Application information

PESD5V0S1UJ and PESD12VS1UJ are designed for the protection of one unidirectional data or signal line from the damage caused by ESD and transient overvoltage. The devices may be used on lines where the signal polarities are either positive or negative with respect to ground.

The PESD5V0S1UJ provides a surge capability of 890 W and the PESD12VS1UJ provides a surge capability of 600 W per line for an 8/20  $\mu$ s waveform.



**Fig 9. Application diagram**

### Circuit board layout and protection device placement

Circuit board layout is critical for the suppression of ESD and Electrical Fast Transient (EFT). The following guidelines are recommended:

1. Place the device as close to the input terminal or connector as possible.
2. The path length between the device and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

## 9. Test information

### 9.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 10. Package outline

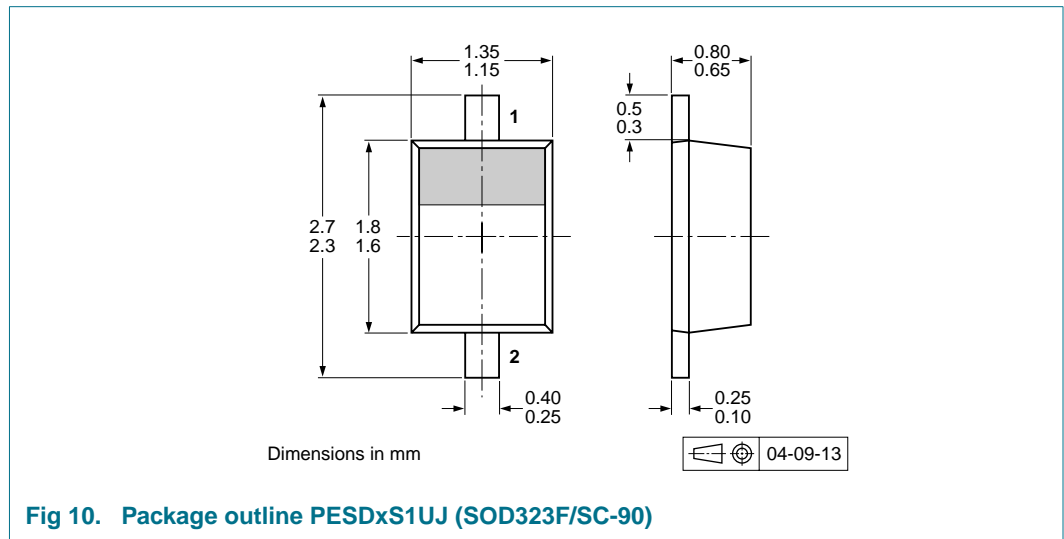


Fig 10. Package outline PESDxS1UJ (SOD323F/SC-90)

## 11. Packing information

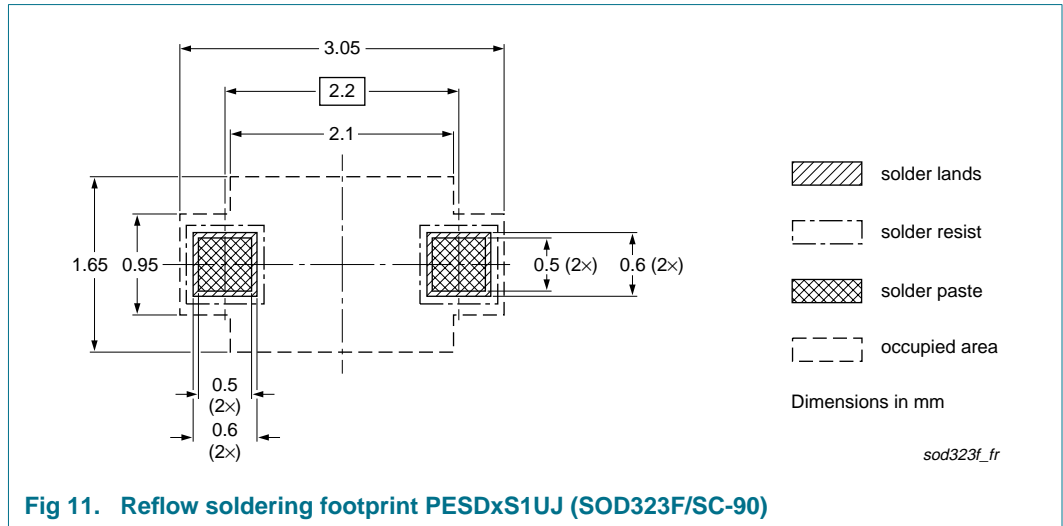
**Table 11. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
PESD5V0S1UJ	SOD323F	4 mm pitch, 8 mm tape and reel	-115	-135
PESD12VS1UJ				

[1] For further information and the availability of packing methods, see [Section 15](#).

## 12. Soldering



### 13. Revision history

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**Table 12. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
PESD5V0S1UJ_PESD12VS1UJ_1	20090603	Product data sheet	-	-

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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